

Title (en)
COPPER ALLOY FOR ELECTRONIC AND ELECTRICAL EQUIPMENT, COPPER ALLOY PLATE STRIP FOR ELECTRONIC AND ELECTRICAL EQUIPMENT, COMPONENT FOR ELECTRONIC AND ELECTRICAL EQUIPMENT, TERMINAL, BUSBAR, AND MOVABLE PIECE FOR RELAYS

Title (de)
KUPFERLEGIERUNG FÜR ELEKTRONISCHE UND ELEKTRISCHE VORRICHTUNGEN, KUPFERLEGIERUNGSBAND FÜR ELEKTRONISCHE UND ELEKTRISCHE VORRICHTUNGEN, KOMPONENTE FÜR ELEKTRONISCHE UND ELEKTRISCHE VORRICHTUNGEN, ANSCHLUSSKLEMME, SAMMELSCHIENE UND BEWEGLICHES TEIL FÜR RELAIS

Title (fr)
ALLIAGE DE CUIVRE POUR MATÉRIEL ÉLECTRONIQUE ET ÉLECTRIQUE, BANDE DE TÔLE EN ALLIAGE DE CUIVRE POUR MATÉRIEL ÉLECTRONIQUE ET ÉLECTRIQUE, COMPOSANT POUR MATÉRIEL ÉLECTRONIQUE ET ÉLECTRIQUE, BORNE, BARRE OMNIBUS ET PIÈCE MOBILE POUR DES RELAIS

Publication
EP 3438299 A4 20191218 (EN)

Application
EP 17775267 A 20170329

Priority

- JP 2016069079 A 20160330
- JP 2017063258 A 20170328
- JP 2017012993 W 20170329

Abstract (en)
[origin: EP3438299A1] A copper alloy for electronic and electrical equipment is provided, including: 0.15 mass% or greater and less than 0.35 mass % of Mg; 0.0005 mass% or greater and less than 0.01 mass% of P; and a remainder which is formed of Cu and unavoidable impurities, in which a conductivity is greater than 75% IACS, a content [Mg] (mass%) of Mg and a content [P] (mass%) of P satisfy a relational expression of $[Mg] + 20 \times [P] < 0.5$, and a content of H is 10 mass ppm or less, a content of O is 100 mass ppm or less, a content of S is 50 mass ppm or less, and a content of C is 10 mass ppm or less.

IPC 8 full level
C22C 9/00 (2006.01); **C22F 1/08** (2006.01); **H01B 1/02** (2006.01)

CPC (source: EP KR US)
C21D 9/46 (2013.01 - US); **C22C 9/00** (2013.01 - EP KR US); **C22F 1/08** (2013.01 - EP KR); **H01B 1/02** (2013.01 - KR); **H01B 1/026** (2013.01 - EP); **H01B 5/02** (2013.01 - KR); **H01H 50/14** (2013.01 - KR); **H01H 50/56** (2013.01 - KR); **H01R 4/58** (2013.01 - KR); **H01R 13/03** (2013.01 - KR US); **H01B 1/02** (2013.01 - US); **H01B 5/02** (2013.01 - US)

Citation (search report)

- [I] JP 2014047378 A 20140317 - MITSUBISHI SHINDO KK
- [I] US 2014209221 A1 20140731 - KUMAGAI JUN-ICHI [JP], et al
- [XA] JP H05311283 A 19931122 - MITSUBISHI SHINDO KK
- [A] JP 2015045083 A 20150312 - MITSUBISHI MATERIALS CORP
- [I] JP 2014025089 A 20140206 - MITSUBISHI SHINDO KK
- See references of WO 2017170733A1

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EP4067517A4; EP4067518A4; EP4074848A4; US11203806B2; US11655523B2; US11104977B2; US10676803B2; US11319615B2; US11920228B2

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DOCDB simple family (application)
EP 17775267 A 20170329; CN 201780005496 A 20170329; JP 2017063258 A 20170328; KR 20187020683 A 20170329; MX 2018011711 A 20170329; TW 106110852 A 20170330